

Report on the Chinese PCB Industry 2019

<https://marketpublishers.com/r/RCB726FECB2EN.html>

Date: September 2019

Pages: 265

Price: US\$ 5,000.00 (Single User License)

ID: RCB726FECB2EN

Abstracts

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PCBs refer to connective circuits and components that are printed onto insulative boards. All modern electronics devices whether it be computers, mobile phones, consumer electronics or electronic toys all use PCBs to a certain extent.

The upstream portion of the PCB industry supply chain deals with base materials including copper laminates, copper foil, copper anodes, prepregs, dry membranes and silver halide. The downstream portion covers computers, communications devices, national defense, industry and medical electronics industries. As the PCB industry's production model is an order-based one, it is common for downstream clients to demand shorter delivery times whenever possible, leading to a closer-knit relationship between upstream manufacturers and downstream clients.

Global PCB output value reached a total of XX billion USD in 2018, a XX% increase over the previous year. Chinese PCB output value reached a total of XX billion USD in 2018, XX% increase over the previous year.

There are a total of XX PCB manufacturers listed in China as of 2018. The Chinese PCB manufacturing industry reached a total of XX billion CNY in 2018, a XX% growth over the previous year.

The driving force of growth in the industry largely stems from downstream demand, and as the consumer electronics industry continues to see large increases in demand, the need for technological innovation and greater production figures will likely increase at a steady rate.

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